# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

## Marketing Name / Model
[List multiple models if applicable.]

HP ZR2240w 21.5-inch LED Backlit IPS Monitor

### Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>IF BD, PW BD</td>
<td>2</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>None on IF BD</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power Cord, VGA Cable, DVI Cable, DP Cable and USB Cable</td>
<td>5</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Stand Base From Display Head
2. Remove Rear Cover From Display Head
3. Remove Front Cover From Display Head
4. Remove Key Board Off From Front Cover
5. Remove Trim Cover From Rear Cover
6. Take Off Screws(x4) From Chassis Cover & Remove Panell
7. Take Screw(x7) Off From P.C.B
8. Take Screw(x6) Off From P.C.B and Remove BKT
9. Remove Mylar From Chassis Cover
10. LCD PANEL EXPLODE
11. Electrolytic Capacitors Over 25mm High & Diameter Dissecting Process
12. Remove Cable Cover Off Stand Base
13. Remove 6 Rubbers From Stand And Base Assembly
14. Remove 13 Screws From Base Assembly
15. Remove Stand Front Cover From Stand Assembly
16. Remove Stand Rear Cover From Stand Assembly
17. Remove Vesa Cover Assembly From Stand BKT
18. Remove Vesa Cover From VESA BKT
19. Remove Pivot Cover From Swivel
20. Remove Tilt Cover and Stand Columb Top Off Stand BKT
21. Remove Stand Columb Front And Rear From Stand BKT
22. The All Parts Of Stand And Base Assembly

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP ZR2240w Disassembly Process

- Jeremy Zhang
- Mechanical Engineer
- Mar-18-2011
External Electric Cables Dissecting Process

1. Remove cable from display head.

2. Dissected completely.
Remove Stand Base From Display Head

1. Pull the quick release button as the red arrow.

2. Remove stand and base assembly from display head.
Remove Rear Cover From Display Head

1. Remove 4 screws from Rear Cover.
Remove Front Cover From Display Head

Lift the aluminum tape

Remove the connector cable

Remove front cover.
5. Take off 1 screw from Front Cover and remove key board from FC.
Take Off Screws From Chassis Cover & Remove Panel

1. Remove connector cable from Chassis cover.

2. Take off 4 Screws from Chassis cover.

3. Remove LVDS cable from Panel.

4. Remove the panel.
1. Take off 7 screws from P.C.B
2. Take off 6 screws from P.C.B
Apart Electrical parts from Bracket assembly

- Power Board
- Interface Board
- Interface wire
- Switch
- Panel
- CHASSIS COVER

Dissected completely.
Remove Mylar From Chassis Cover
LCD PANEL EXPLODE

Step 1: Put the LCM to the back side

Step 2: Unscrew the 3 points of screw

Step 3: Remove the Metal C/S

Step 4: Separate Case Top (Bottom → Right or Left)

Step 5: Detach Conductive tape

Step 6: Detach PCB from the Back of C/B

Step 7: Separate Board Ass’y
LCD PANEL EXPLODE

Step 8: Loosen the screw (6 Point)

Step 9: Separate Guide Panel (Bottom)

Step 10: Separate Guide Panel (Left & Right)

Step 11: Separate Guide Panel (Top)

Step 12: Separate Guide Panel

Step 13: Separate Optical Sheet

Step 14: Separate LGP

Final: Cover Ass’y
LCD PANEL EXPLODE

Step 7: Separate wires from the tape (2 Point)

Step 8: Unfix B/L Screws (6ea)

Step 9: Pull lamp housing with hands normal to LCM (*Be careful not to break the Lamp)

Step 10: Separated lamp ass'y (UP)
Electrolytic Capacitors Over 25mm High & Diameter Dissecting Process

1. Heats Up, Dissolved Tin Lead.
2. Takes Down The Capacitor.
3. Dissecting To Complete.
   (Next Page Have Description)
Electrolytic Capacitors Process Drawing
Remove Cable Cover Off Stand Base
Remove 6 Rubbers From Stand And Base Assembly
Remove 13 Screws From Base Assembly
Remove Stand Front Cover From Stand Assembly
Remove Stand Rear Cover From Stand Assembly

Take off 3 screws from Stand Assembly
Remove Vesa Cover Assembly From Stand BKT

Take off 4 screws from Stand BKT
Remove Vesa Cover From VESA BKT

Take off 4 screws from VESA BKT
Remove Pivot Cover From Swivel

Take off 2 screws from Stand BKT
Remove Tilt Cover and Stand Columb Top Off Stand BKT

Take off 2 screws from Stand BKT
Remove Stand Column From Front And Rear From Stand BKT

Take off 3 screws from Stand BKT
The All Parts Of Stand And Base Assembly